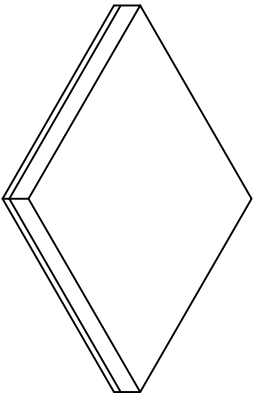


REVISION HISTORY						DATE
REV	REV NUMBER	DESCRIPTION	ORIGINATOR	DRAWING FILE NAME	GREEN FILE NAME	
00	C06147	INITIAL RELEASE PER DCN C06147	MCN	N/A	N/A	05/12/00
01	C1167	ADDED 88 SOLDER BALL FOOTPRINT	SDEFO	N/A	N/A	04/09/01
02	N/A	ADDED 100 BGA FOOTPRINT AND SH 4	CBURR	N/A	N/A	09/22/03
03	N/A	CORRECTED 100 BGA FOOTPRINT ON SH 4	CBURR	N/A	N/A	11/05/03



7. REFERENCE SPECIFICATIONS:
A. MWM SPEC. #001-0531-2234: PACKING OPERATION PROCEDURE.
B. MWM SPEC. #001-0519-2062: MARKING.

6. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.

4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BALLS IS 100.
3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 10 X 10.
2. THE BASIC SOLDER BALL GRID PITCH IS 0.50mm.
1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.
- NOTES: UNLESS OTHERWISE SPECIFIED

UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE IN MILLIMETERS		TYPED IMAGE PROJECTION		FIRST TECHNOLOGY, INC. Customer: Avnet, USA Avnet Technology, Inc. Avnet Technology Philippines, Inc. Avnet, Inc., Philippines		TITLE		PACKAGE OUTLINE - MAF: 10 X 10 MATRIX, 6.00mm X 6.00mm X 1.00mm, 0.50mm MOLD CAP, 0.50mm BALL, 0.50mm PITCH, DAMINATE SUBSTRATE, MWM		SHEET 1 OF 4	
DECIMAL	ANGULAR	3:1									
XX.XX	XX.X	XX.X	XX.X	XX.X	XX.X	XX.X	XX.X	XX.X	XX.X	XX.X	XX.X
XX.XX	XX.X	XX.X	XX.X	XX.X	XX.X	XX.X	XX.X	XX.X	XX.X	XX.X	XX.X
INTERPRET DIM AND TOL PER	ASME Y14.5M - 1994										
APPROVALS	DATE										
DESIGNED: JANOBL	04/19/99										
CHECKED: JINICK	04/19/99										
PROJECT MANAGER	04/19/99										
DESIGNED: CROCH	05/12/99										
PROJECT MANAGER	05/12/99										
DO NOT SCALE DRAWING											

